

ZENITE® 650

Zenite® 650 is designed for high dielectric constant and low dissipation factor

Rheological properties

Moulding shrinkage range, parallel	%	ISO 294-4, 2577
Moulding shrinkage range, normal	0.6 %	ISO 294-4, 2577

Typical mechanical properties

Tensile Modulus	18000 MPa	ISO 527-1/-2
Stress at break, 50mm/min	143 MPa	ISO 527-1/-2
Strain at break, 50mm/min	1.5 %	ISO 527-1/-2
Flexural Modulus	16000 MPa	ISO 178
Flexural Strength	197 MPa	ISO 178
Charpy impact strength, 23°C	24 kJ/m ²	ISO 179/1eU

Thermal properties

Temp. of deflection under load, 1.8 MPa	278 °C	ISO 75-1/-2
---	--------	-------------

Electrical properties

Volume resistivity	>1E13 Ohm.m	IEC 62631-3-1
Surface resistivity	>1E14 Ohm	IEC 62631-3-2
Electric strength	24 kV/mm	IEC 60243-1
Relative permittivity, printed circuits and boards, 2.5 GHz	12	IEC 61189-2-721
Dissipation factor, printed circuits and boards, 2.5 GHz	80 E-4	IEC 61189-2-721

Other properties

Density	2020 kg/m ³	ISO 1183
---------	------------------------	----------

Injection

Drying Temperature	150 °C
Drying Time, Dehumidified Dryer	6 h
Max. mould temperature	100 °C

